



Material Content Data Sheet



Sales Product Name		TLE6209R		Issued		28. August 2013			
MA#		MA000983006							
Package		PG-DSO-20-65		Weight*		2033.19 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	21.764	1.07	1.07	10704	10704	
leadframe	inorganic material	phosphorus	7723-14-0	0.359	0.02		176		
	non noble metal	zinc	7440-66-6	1.435	0.07		706		
	non noble metal	iron	7439-89-6	28.697	1.41		14114		
	non noble metal	copper	7440-50-8	1165.200	57.31	58.81	573089	588085	
wire	non noble metal	copper	7440-50-8	1.412	0.07	0.07	694	694	
encapsulation	organic material	carbon black	1333-86-4	1.578	0.08		776		
	plastics	epoxy resin	-	72.579	3.57		35697		
	inorganic material	silicondioxide	60676-86-0	714.747	35.15	38.80	351539	388012	
leadfinish	non noble metal	tin	7440-31-5	10.336	0.51	0.51	5084	5084	
plating	noble metal	silver	7440-22-4	0.686	0.03	0.03	337	337	
solder	noble metal	silver	7440-22-4	0.216	0.01		106		
	non noble metal	tin	7440-31-5	0.144	0.01		71		
	non noble metal	lead	7439-92-1	14.043	0.69	0.71	6907	7084	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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